# **BMD-341**

# Stand-alone Bluetooth 5 low energy modules

**Data sheet** 



#### Abstract

This technical data sheet describes the BMD-341 stand-alone Bluetooth<sup>®</sup> low energy module. The OEMs can embed their own application on top of the integrated Bluetooth low energy stack using Nordic Semiconductor SDK or Arm<sup>®</sup> Mbed<sup>™</sup> integrated development environment (IDE).



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Engineering sample	Advance information	Data based on early testing. Revised and supplementary data will be published later.			
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#### This document applies to the following products:

Product name	Type number	Firmware version	PCN reference	Product status
BMD-341	BMD-341-A-R-00	N/A	N/A	Initial production

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# **1** Functional description

The BMD-341 is an advanced, highly flexible, ultra-low power multiprotocol SoM that enables Bluetooth 5 (Bluetooth low energy) and IEEE 802.15.4 (Thread and Zigbee) connectivity for portable, extremely low power embedded systems. With an ARM<sup>®</sup> Cortex<sup>™</sup>-M4F CPU, integrated 2.4 GHz transceiver, and a U.FL connector for an external antenna, the BMD-341 provides a complete RF solution allowing faster time to market with reduced development costs. Providing full use of the Nordic Semiconductor nRF52840 capabilities and peripherals, the BMD-341 can power the most demanding applications, all while simplifying designs and reducing BOM costs. The BMD-341 is an ideal solution for designs that require the latest Bluetooth 5 features or 802.15.4 based networking for Thread. Increased integration with built in USB and 5.5V compatible DC/DC supply reduces design complexity and BOM cost, while expanding possible applications. BMD-341 designs are footprint compatible with the BMD-300/301/330/360, providing low-cost flexibility for tiered product lineups.

#### 1.1 Features

- Based on the Nordic Semiconductor nRF52840 SoC
- Bluetooth 5 2M low energy, Advertising Extensions, CSA #2, Coded PHY (Long Range)
- Bluetooth mesh
- IEEE 802.15.4 with Thread and Zigbee support
- Complete RF solution with U.FL connector for an external antenna
- Integrated DC-DC converter
- No external components required
- ARM<sup>®</sup> Cortex<sup>™</sup>-M4F 32-bit processor
- ARM<sup>®</sup> TrustZone<sup>®</sup> Cryptocell 310 security
- True random number generator
- Serial Wire Debug (SWD)
- Nordic Semiconductor SoftDevice ready
- 1 MB embedded flash memory
- 256 KB RAM
- 48 General Purpose I/O Pins
- 12-bit/200 KSPS ADC
- One Full-Speed USB (12 Mbps)
- Four SPI Master/Slave (8 Mbps)
- Quad SPI with Execute in Place (XIP)
- Low power comparator
- Temperature sensor
- Two 2-wire Master/Slave (I2C compatible)
- I2S audio interface
- Two UARTs (w/ CTS/RTS and DMA)
- 20 channel CPU independent Programmable Peripheral Interconnect (PPI)
- Quadrature Demodulator (QDEC)
- 128-bit AES HW encryption
- 5 x 32 bit, 3 x 24 bit Real Timer Counters (RTC)
- NFC-A tag interface for OOB pairing
- Dimensions: 15.0 x 10.2 x 1.9 mm



## 1.2 Applications

- Climate control
- Lighting products
- Safety and security
- Home appliances
- Access control
- Internet of Things
- Home Health Care
- Advanced Remote Controls
- Smart Energy Management
- Low-Power Sensor Networks
- Interactive Entertainment Devices
- Environmental Monitoring
- Hotel Automation
- Office Automation

## 1.3 Block diagram

#### BMD-341 Bluetooth 5 Low Energy SoC Module

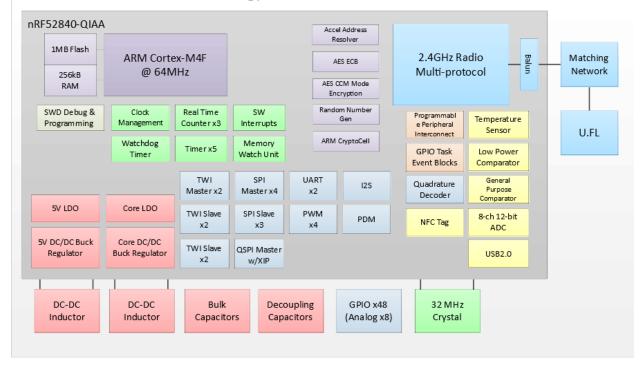


Figure 1: Block diagram of BMD-341



# 1.4 Radio performance

Detail	Description
Bluetooth	
Bluetooth version	Bluetooth 5 Low Energy, Concurrent Central & Peripheral (S140) Coded PHY (Long Range), 2 Mbps & 1 Mbps PHY, Advertising Extensions, CSA #2, Bluetooth mesh
Security	AES-128
LE connections	Concurrent central, observer, peripheral, and broadcaster roles with up to twenty concurrent connections along with one Observer and one Broadcaster (S140)
IEEE 802.15.4	
Thread stack	OpenThread, Thread 1.1 certified
Thread security	AES-128, ARM® Cryptocell accelerated
Zigbee stack	Zigbee 3.0 compliant
Radio	
Frequency	2.360 GHz to 2.500 GHz
Modulations	GFSK at 1 Mbps and 2 Mbps, QPSK at 250 Kbps
Transmit power	+8 dBm maximum (at IC pin)
Receiver sensitivity	-96 dBm (BLE 1Mbps PHY)
Antenna	U.FL connector for an external antenna
Current consumption	
TX only @ +8 dBm, 0 dBm @ 3V, DCDC enabled	14.8 mA, 4.8 mA
TX only @ +8 dBm, 0 dBm	32.7 mA, 10.6 mA
RX only @ 1 Mbps @ 3V, DCDC enabled	4.6 mA
RX only @ 1 Mbps	9.9 mA
CPU @ 64 MHz from flash, from RAM	6.3 mA, 5.2 mA
CPU @ 64 MHz from flash, from RAM @ 3V, DCDC enabled	3.3 mA, 2.8 mA
System Off, On (Supply on VCC), no RAM retention	0.4 μΑ, 0.97 μΑ
System Off, On (Supply on VCC), full 256 KB RAM retention	1.86 μΑ, 2.35 μΑ
Dimensions	
BMD-341	Length: 15.0 mm ± 0.3mm
	Width: 10.2 mm ± 0.3mm
	Height: 1.9 mm ± 0.1mm
Hardware	
Interfaces	SPI Master/Slave x 4 Quad SPI x 1 UART x 2 Two-Wire Master/Slave (I2C) x 2 GPIO x 48 I2S x1 PWM x 12 PDM x 1 USB 2.0 x 1 Analog input x 8
Power supply	VCC: 1.7 V to 3.6 V, 1.75 V required to start DCDC VCCH: 2.5 V to 5.5 V VBUS: 4.35 V to 5.5 V (For USB operation)

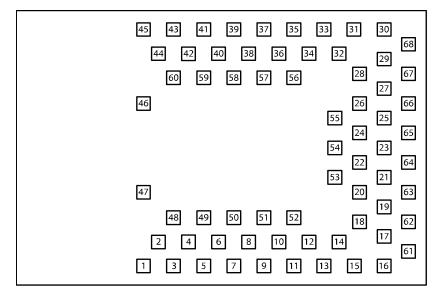


Detail	Description		
Temperature range	-40 °C to +85 °C		
Certifications			
USA (FCC)	FCC part 15.247 modular certification		
	FCC ID: XPYBMD341		
Canada (ISED)	Innovation, Science and Economic Development Canada RSS-247 modular		
Europe (CE) (Pending)	certification IC: 8595A-BMD341		
	EN 60950-1: A2:2013 3.1 (a): Health and Safety of the User		
	EN 301 489-1 V2.1.1 & 3.1 (b): Electromagnetic Compatibility		
	EN 301 489-17 V3.1.1		
Australia / New Zealand (RCM) (Pending)	EN 300 328 V2.1.1 3.2: Effective use of spectrum allocated		
Bluetooth	AS/NZS 4268:2017, Radio equipment and systems – Short range devices		
	BMD-341 RF-PHY Component (Tested) – DID: D040773; QDID: 95452		
Export			
BMD-341	ECCN: 5A992.C, Exception 742.15(b)(1)		
	HTS: 8473.30.1180		
Naudia Canaisan duatan a DEE2040	nRF52840 Product Specification		
Nordic Semiconductor nRF52840	nRF5 Software Development Kit		



# 2 Pin definition

# 2.1 Pin assignment



#### Figure 2: BMD-341 Pin assignment (Top view)

No.	Name	I/O	Description	nRF52 pin	Remarks
1	GND	Power	Electrical Ground	GND	
2	GND	Power	Electrical Ground	GND	
3	GND	Power	Electrical Ground	GND	
4	GND	Power	Electrical Ground	GND	
5	GND	Power	Electrical Ground	GND	
6	P0.25	I/O	GPIO	P0.25	
7	P0.26	I/O	GPIO	P0.26	
8	P0.27	I/O	GPIO	P0.27	
9	P0.28	I/O	GPIO/AIN4	P0.28	Standard drive, low frequency I/O only (<10 kHz)
10	P0.29	I/O	GPIO/AIN5	P0.29	Standard drive, low frequency I/O only (<10 kHz)
11	P0.30	I/O	GPIO/AIN6	P0.30	Standard drive, low frequency I/O only (<10 kHz)
12	P0.31	I/O	GPIO/AIN7	P0.31	Standard drive, low frequency I/O only (<10 kHz)
13	P0.00	I/O	GPIO/XTAL1 (32.768 kHz)	P0.00	
14	P0.01	I/O	GPIO/XTAL2 (32.768 KHz)	P0.01	
15	P0.02	I/O	GPIO/AIN0	P0.02	Standard drive, low frequency I/O only (<10 kHz)
16	GND	Power	Electrical Ground	GND	
17	VCC	Power In/Out	LV Mode: 1.7 V to 3.6 V in HV Mode: 1.8 V to 3.3 V supply out <sup>1</sup>	VCC	An internal 4.7 $\mu$ F bulk capacitor is included on the module. However, it is good design practice to add additional bulk capacitance as required for your application, i.e. those with heavy GPIO usage and/or current draw.
18	GND	Power	Electrical Ground	GND	
19	P0.03	I/O	GPIO/AIN1	P0.03	Standard drive, low frequency I/O only (<10 kHz)
20	P0.04	I/O	GPIO/AIN2	P0.04	
21	P0.05	I/O	GPIO/AIN3	P0.05	
22	P0.06	I/O	GPIO	P0.06	
23	P0.07	I/O	GPIO/TRACECLK	P0.07	



No.	Name	I/O	Description	nRF52 pin	Remarks
24	P0.08	I/O	GPIO	P0.08	
25	P0.09	I/O	GPIO/NFC1	P0.09	Standard drive, low frequency I/O only (<10 kHz)
26	P0.10	I/O	GPIO/NFC2	P0.10	Standard drive, low frequency I/O only (<10 kHz)
27	P0.11	I/O	GPIO/TRACEDATA[2]	P0.11	
28	P0.12	I/O	GPIO/TRACEDATA[1]	P0.12	
29	GND	Power	Electrical Ground	GND	
30	GND	Power	Electrical Ground	GND	
31	P0.13	I/O	GPIO	P0.13	
32	P0.14	I/O	GPIO	P0.14	
33	P0.15	I/O	GPIO	P0.15	
34	P0.16	I/O	GPIO	P0.16	
35	P0.17	I/O	GPIO	P0.17	
36	P0.21	I/O	GPIO	P0.21	
37	P0.19	I/O	GPIO	P0.19	
38	P0.20	I/O	GPIO	P0.20	
39	P0.18	I/O	GPIO/RESET_N	P0.18	
40	P0.22	1/0	GPIO	P0.22	
40	P0.23	1/0	GPIO	P0.23	
41	P0.23	1/0	GPIO	P0.23	
42	SWCLK		SWD Clock	SWCLK	
43	SWDIO	I/O	SWD IO	SWDIO	
		•			
45	GND GND	Power	Electrical Ground Electrical Ground	GND	
46 47	GND	Power	Electrical Ground	GND GND	
47	P1.05	Power I/O	GPIO	P1.05	Standard drive, low frequency I/O only (<10 kHz)
		•			
49	P1.06	1/0	GPIO	P1.06	Standard drive, low frequency I/O only (<10 kHz)
50	P1.07	I/O	GPIO	P1.07	Standard drive, low frequency I/O only (<10 kHz)
51	P1.08	I/O	GPIO	P1.08	
52	P1.09	I/O	GPIO/TRACEDATA[3]	P1.09	
53	P1.10	I/O	GPIO	P1.10	Standard drive, low frequency I/O only (<10 kHz)
54	P1.11	I/O	GPIO	P1.11	Standard drive, low frequency I/O only (<10 kHz)
55	GND	Power	Electrical Ground	GND	
56	P1.00	I/O	GPIO/TRACEDATA[0]/SWO	P1.00	
57	P1.01	I/O	GPIO	P1.01	Standard drive, low frequency I/O only (<10 kHz)
58	P1.02	I/O	GPIO	P1.02	Standard drive, low frequency I/O only (<10 kHz)
59	P1.03	I/O	GPIO	P1.03	Standard drive, low frequency I/O only (<10 kHz)
60	P1.04	I/O	GPIO	P1.04	Standard drive, low frequency I/O only (<10 kHz)
61	P1.12	I/O	GPIO	P1.12	Standard drive, low frequency I/O only (<10 kHz)
62	P1.13	I/O	GPIO	P1.13	Standard drive, low frequency I/O only (<10 kHz)
63	P1.14	I/O	GPIO	P1.14	Standard drive, low frequency I/O only (<10 kHz)
64	P1.15	I/O	GPIO	P1.15	Standard drive, low frequency I/O only (<10 kHz)
67	USB-D-	I/O	USB Data-	USB-D-	
68	USB-D+	I/O	USB Data+	USB-D+	
66	VBUS	Power	USB PHY supply: 4.35 V to 5.5 V in	VBUS	



No.	Name	I/O	Description	nRF52 pin	Remarks
			Connect to USB Host device 5 V supply	5	
65	VCCH	Power	LV Mode: Connect to VCC HV Mode: 2.5 V to 5.5 V in	VCCH	An internal 4.7 μF bulk capacitor is included on the module. However, it is good design practice to add additional bulk capacitance as required for your application, i.e. those with heavy GPIO usage and/or current draw.

#### Table 1: BMD-341 pin-out

1: In HV mode, VCC acts as a regulated supply that can power other external devices. The voltage output of VCC can be configured in software but is limited to no more than VCCH-0.3 V. In System Off mode, VCC can supply no more than 1mA.

# 2.2 Peripheral pins

The BMD-341 features a pin multiplexing system that allows most internal peripherals, such as UART and SPI, to be used on any GPIO pin. This freedom in pin choice enables better optimization of designs and PCB layout. Note that only one peripheral signal can be multiplexed to a GPIO pin at a time. Some functions are restricted to certain pins due to additional internal circuitry required by the interface. These include: Trace signals, analog inputs, XTAL signals, USB signals, SWD interface, and reset. See Table 2 for details:

Peripheral	Signal	Pin Options	
UARTO, UART1,	All	P0.00-P0.31, P1.00-P1.15	
12C0, 12C1,			
SPIO, SPI1, SPI2, SPI3,			
12S0, QSP10, PDN0,			
PWM0, PWM1, PWM2, PWM3			
ADC, COMP, LPCOMP	All	P0.02-P0.05, P0.28-P0.31 (AIN0-AIN7)	
NFC	NFC1	P0.09	
	NFC2	P0.10	
Reset	RESET_N	P0.18	
Trace	TRACECLK	P0.07	
	SWO/TRACEDATA[0]	P1.00	
	TRACEDATA[1]	P0.12	
	TRACEDATA[2]	P0.11	
	TRACEDATA[3]	P1.09	
SWD	SWD Clock	SWCLK	
	SWD IO	SWDIO	
32.768 kHz Crystal	XTAL1	P0.00	
	XTAL2	P0.01	
USB	USB Data +	USB-D+	
	USB Data -	USB-D-	

#### **Table 2: Peripheral pin options**

Some peripherals on the BMD-341 share the same memory location for their registers. This means that only one of these peripherals can be used at a time. It is possible to switch between peripherals sharing a register location by clearing and reinitializing the associated configuration registers. See the Nordic Semiconductor nRF52840 Product Specification for details.

Peripheral ID	Base Address	Shared Peripherals		
3	0x40003000	SPIO	12C0	
4	0x40004000	SPI1	I2C1	

Table 3: Peripherals with shared registers



#### 2.3 BMD-300 series footprint compatibility and migration

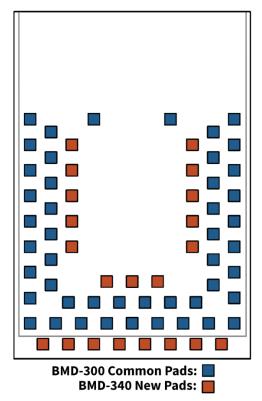


Figure 3: BMD-340/341 and BMD-300/301/330/360 Footprint comparison

The BMD-341 footprint is identical to the BMD-340 and has been designed to allow for backwards compatibility with the BMD-300, BMD-301, BMD-330, and BMD-360 modules with pins 1 through 47 of the BMD-341 directly mapping to the same pin numbers on the BMD-300/301/330/360. This allows BMD-300, BMD-301, BMD-330, and BMD-360 modules to be placed directly onto the BMD-341 footprint for easy migration and enabling tiered product design. Care should be taken to follow ground plane and keep-out areas if designing for modules with an integrated antenna.

Generally, all pin names and functions remain the same, except for some differences noted below. Pins 48 through 68 of the BMD-341 footprint are new pads used for new features that are not present on the BMD-300/301/330/360 modules, such as USB interface and additional GPIO and power connections.

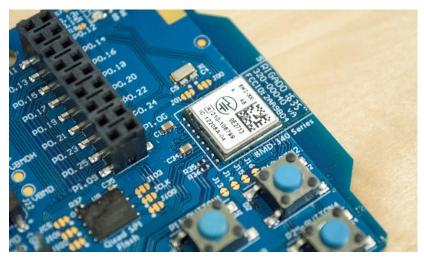


Figure 4: BMD-300 Module soldered to BMD-340/341 footprint



#### 2.3.1 BMD-300/301/330/360 to BMD-341 pad differences

Due to changes in the nRF52840 SoC used by the BMD-341, not all functions (such as SWO/TRACE signals) are found on the same pins as on the BMD-300/301/330/360. Particularly of note is the reset pin function which on the BMD-341 is now available on P0.18 instead of P0.21 as on the BMD-300/301/330/360. To maintain pin for pin compatibility of the reset signal, P0.18 and P0.21 have swapped pad locations on the BMD-341 footprint. These differences are detailed in Table 4 below:

Pin	BMD-300/301	BMD-300/301	BMD-341	BMD-341
	Name	Function	Name	Function
39	P0.21	GPIO/RESET_N	P0.18	GPIO/RESET_N
38	P0.20	GPIO/TRACECLK	P0.20	GPIO
36	P0.18	GPIO/TRACEDATA[0]/SWO	P0.21	GPIO
34	P0.16	GPIO/TRACEDATA[1]	P0.16	GPIO
33	P0.15	GPIO/TRACEDATA[2]	P0.15	GPIO
32	P0.14	GPIO/TRACEDATA[3]	P0.14	GPIO
23	P0.07	GPIO	P0.07	GPIO/TRACECLK
56	N/A	N/A	P1.00	GPIO/TRACEDATA[0]/SWO
28	P0.12	GPIO	P0.12	GPIO/TRACEDATA[1]
27	P0.11	GPIO	P0.11	GPIO/TRACEDATA[2]
52	N/A	N/A	P1.09	GPIO/TRACEDATA[3]

Table 4: BMD-300/301/330 to BMD-341 Pad differences

#### 2.3.2 BMD-300/301/330/360 to BMD-341 design migration

Existing designs incorporating the BMD-300, BMD-301, BMD-330 or BMD-360 module can be migrated over to the BMD-341 with the addition of a single footprint pad for VCCH (pin 65). This migration option is only suitable for applications that do not require the new USB interface, additional GPIO, or higher supply voltage functionality. The VCCH pad must be present and electrically connected to the same supply as VCC for the module to operate correctly. Vias underneath the BMD-341 should be tented to avoid shorts to unused module pads. Firmware written for the BMD-300/301/330/360 can generally be ported to the BMD-341 with minimal effort. See the Nordic Semiconductor SDK documentation for details.

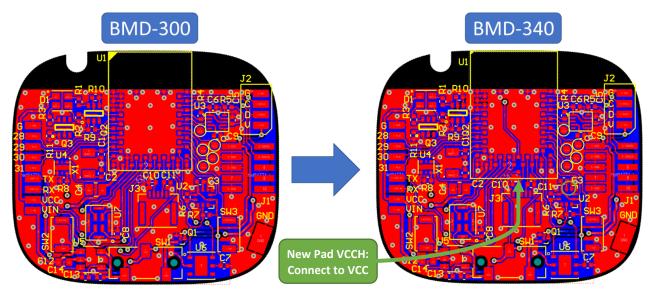


Figure 5: BMD-300 to BMD-341 Migration Example



Using the BMD-341 minimal footprint, with only the additional VCCH pad added, allows BMD-300 designs to gain the following BMD-341 features with typically minor layout re-work:

- Bluetooth 5 long range modes
- IEEE 802.15.4 (Thread and Zigbee) connectivity
- Doubled Flash memory (1 MB vs. 512 KB)
- Quadrupled RAM (256 KB vs. 64 KB)
- ARM® TrustZone® Cryptocell 310 security co-processor

To take advantage of new hardware features, such as the additional UART and Quad SPI interface, the full BMD-341 footprint should be used. Designs that require the 5V DCDC converter, trace interface, USB interface, or the additional GPIO (P1.00-P1.15) must use the full BMD-341 footprint.

Since the BMD-300/301/330/360 can be soldered to the full BMD-340/341 footprint, it is highly recommended that all new BMD-300/301/330/360 and BMD-340/341 projects use the full

BMD-340/341 footprint. When migrating designs, the full BMD-341 footprint should be used whenever possible as it is better suited for use with mass production SMT processing. Care should be taken to follow ground plane and keep-out areas if designing for modules with an integrated antenna.

#### 2.4 BMD-341 fan-out example

The following figure is a BMD-341 fan-out example on a simple 2-layer PCB. This example is powered via VCCH from a USB connection. See section 3.3 for details on power and DCDC operation.

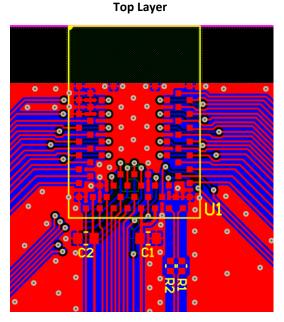


Figure 6: BMD-341 two-layer fan-out example

# Bottom Layer



# **3** Electrical specifications

Stressing the device above one or more of the ratings listed in the Absolute maximum rating section may cause permanent damage. These are stress ratings only. Operating the module at these or at any conditions other than those specified in the Operating conditions section of this document should be avoided. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

F

Operating condition ranges define those limits within which the functionality of the device is guaranteed. Where application information is given, it is advisory only and does not form part of the specification.

#### 3.1 Absolute maximum ratings

Symbol	Description	Min	Max	Unit	
V <sub>CC_MAX</sub>	Voltage on VCC supply pin	-0.3	3.9	V	
V <sub>CCH_MAX</sub>	Voltage on VCCH supply pin	-0.3	5.8	V	
V <sub>BUS_MAX</sub>	Voltage on VBUS supply pin	-0.3	5.8	V	
V <sub>IO_MAX</sub>	Voltage on GPIO pins ( $V_{cc}$ > 3.6V)	-0.3	3.9	V	
V <sub>IO_MAX</sub>	Voltage on GPIO pins ( $V_{CC} \le 3.6V$ )	-0.3	V <sub>cc</sub> +0.3 V	V	
Ts	Storage Temperature Range	-40	125	°C	

Table 5: Absolute maximum ratings

The product is not protected against overvoltage or reversed voltages. If necessary, voltage spikes exceeding the power supply voltage specification, given in table above, must be limited to values within the specified boundaries by using appropriate protection devices.

# 3.2 Operating conditions

- Unless otherwise specified, all operating condition specifications are at an ambient temperature of 25 °C and a supply voltage of 3.3 V.
- ⚠ Operation beyond the specified operating conditions is not recommended and extended exposure beyond them may affect device reliability.

Symbol	Parameter	Min	Тур.	Max	Unit
V <sub>CC_IN</sub>	VCC operating supply voltage in	1.7	3.0	3.6	V
V <sub>CC_START</sub>	VCC DCDC starting voltage	1.75	-	-	V
V <sub>CCH_HV</sub>	VCCH operating supply voltage in	2.5	5.0	5.5	V
V <sub>BUS_IN</sub>	VBUS operating supply voltage in	4.35	5.0	5.5	V
T <sub>R_VCC</sub>	VCC Supply rise time (0 V to 1.7 V)	-	-	60	ms
T <sub>R_VCCH</sub>	VCCH Supply rise time (0 V to 3.7 V)	-	-	100	ms
T <sub>A</sub>	Operating Ambient Temperature Range	-40	25	85	°C

Table 6: Operating conditions

# 3.3 Power and DCDC configuration

The BMD-341 has two internal regulator stages that each contain an LDO and DCDC regulator. The first regulator, REGO, is fed by the VCCH pin and can accept a source voltage of 2.5 V to 5.5 V. The output of REGO is connected to the VCC pin and the input of the second regulator stage REG1. REG1 supplies power to the module core and can accept an input source voltage of 1.7 V to 3.6 V. Depending on how the VCC and VCCH pins are connected, the module will operate in one of two modes:



Normal/Low Voltage (LV) or High Voltage (HV). The voltage present on the VCC pin is always the GPIO high logic level voltage, regardless of power mode.

To enter LV Mode, the same source voltage is applied to both the VCC and VCCH pins causing REG0 to automatically shut down leaving only the REG1 stage active. To enter HV, the source voltage is only applied to VCCH causing the VCC pin to become an output source supplied by REG0.

Mode	Pin	Name	Connection	
Normal (LV)	17	VCC	1.7 V to 3.6 V source in	
	65	VCCH	Same source as VCC	
High Voltage (HV)	17	VCC	1.8 V to 3.3 V supply out	
	65	VCCH	2.5 V to 5.5 V source in	

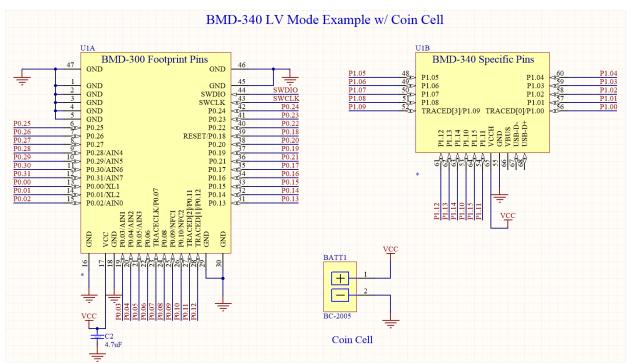
Table 7: Power mode pin connections

Important: In both LV and HV mode, the GPIO logic level voltage is determined by the VCC pin. In HV mode, all external devices that are connected to the BMD-341's GPIO must either be powered by the module (from VCC) or use level translation.

REGO can supply a maximum current of 25 mA for the module and external circuits in System On Mode and 1 mA in System Off Mode. External circuits powered from VCC in HV mode should be limited to no more than 5 mA to ensure stability at all radio transmit power levels.

#### 3.3.1 USB power

The USB interface on the BMD-341 can be used when the module is in either Normal (LV) or High Voltage (HV) mode. The BMD-341 USB PHY is powered by a dedicated, internal LDO regulator that is fed by the VBUS pin (66). This means that applying power to only the VBUS pin will not power the rest of the module. In order for the USB PHY to operate, VBUS must be externally powered.



### 3.3.2 Normal (LV) power mode examples

Figure 7: BMD-340/341 LV Mode w/ Coin Cell Example



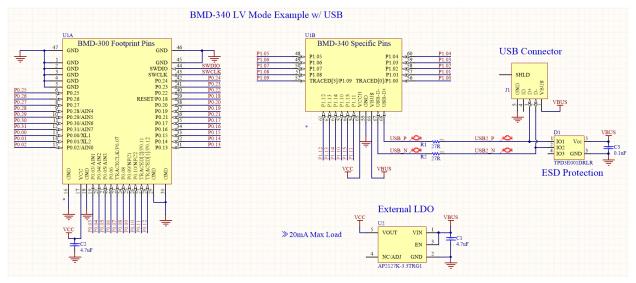


Figure 8: BMD-340/341 LV Mode w/ USB and external regulator

#### 3.3.3 High voltage (HV) power mode examples

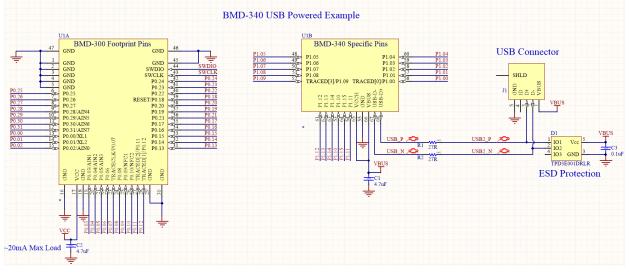


Figure 9: BMD-340/341 USB-powered HV mode example



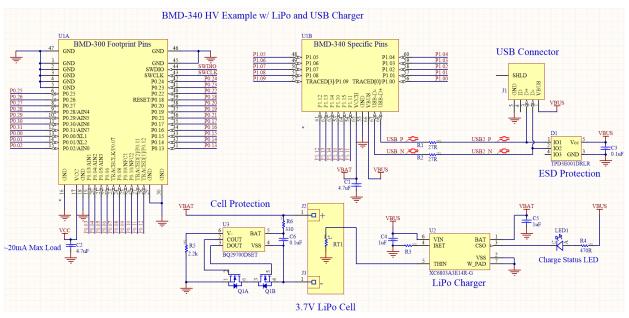


Figure 10: BMD-340/341 LiPo-powered HV example with USB charger

Important: The LiPo circuit above is meant to be a generic example of how the BMD-341's power modes can be used. Great care must be taken when integrating Lithium-Ion batteries into a design. Protection circuits suitable for the type of battery used and the application must always be implemented.

## 3.4 General purpose I/O

The general purpose I/O is organized as two ports enabling access and control of the 48 available GPIO pins. The first port allows access of P0.00 to P0.31, similar to the one port available on the BMD-300/301. The second port, new to the BMD-341, allows access to P1.00 to P1.15. Each GPIO can be accessed individually with the following user configurable features:

• Input/output direction

⚠

- Output drive strength
- Internal pull-up and pull-down resistors
- Wake-up from high- or low-level triggers on all pins
- Trigger interrupt on all pins
- All pins can be used by the PPI task/event system; the maximum number of pins that can be interfaced through the PPI at the same time is limited by the number of GPIOTE channels
- All pins can be individually configured to carry serial interface or quadrature demodulator signals

VIH	Input High Voltage	0.7 x VCC			
		0.7 × 000	-	VCC	V
VIL	Input Low Voltage	GND	-	0.3 x VCC	V
VOH	Output High Voltage	VCC - 0.4	-	VCC	V
VOL	Output Low Voltage	GND	-	GND + 0.4	V
RPU	Pull-up Resistance	11	13	16	kΩ
RPD	Pull-down Resistance	11	13	16	kΩ

Table 8: GPIO

#### 3.5 Module reset

GPIO pin P0.18 may be used for a hardware reset. In order to utilize P0.18 as a hardware reset, the UICR registers PSELRESET[0] and PSELRESET[1] must be set alike, to the value of 0x7FFFFD2.



When P0.18 is programmed as RESET\_N, the internal pull-up is automatically enabled. Nordic Semiconductor example applications and development kits program P0.18 as RESET\_N.

# 3.6 Debug and programming

The BMD-341 supports the two pin Serial Wire Debug (SWD) interface and offers flexible and powerful mechanism for non-intrusive debugging of program code. Breakpoints, single stepping, and instruction trace capture of code execution flow are part of this support.

The BMD-341 also supports ETM and ITM trace. The trace data from the ETM and the ITM is sent to an external debugger via a 4-bit wide parallel trace port. In addition to parallel trace, the TPIU supports serial trace via the Serial Wire Output (SWO) trace protocol.

## 3.7 Clocks

The BMD-341 requires two clocks, a high frequency clock and a low frequency clock. The high frequency clock is provided on-module by a high-accuracy 32 MHz crystal as required by the nRF52840 for radio operation.

The low frequency clock can be provided internally by an RC oscillator or synthesized from the fast clock, or externally by a 32.768 kHz crystal. An external crystal provides the lowest power consumption and greatest accuracy. Using the internal RC oscillator with calibration provides acceptable performance for Bluetooth low energy applications at a reduced cost and slight increase in power consumption.

The ANT protocol requires the use of an external crystal.

**f**<sub>TOL\_LFXO\_BLE</sub> and f<sub>TOL\_LFXO\_ANT</sub> are the maximum allowed for Bluetooth low energy and ANT applications. Actual tolerance depends on the crystal used.

#### 3.7.1 32.768 kHz crystal (LFXO)

Symbol	Parameter	Тур.	Max.	Unit
F <sub>NOM_LFXO</sub>	Crystal frequency	32.768	-	kHz
F <sub>TOL_LFXO_BLE</sub>	Frequency tolerance, Bluetooth low energy applications	-	±500	ppm
f <sub>tol_lfxo_ant</sub>	Frequency Tolerance, ANT applications	-	±50	ppm
C <sub>L_LFXO</sub>	Load Capacitance	-	12.5	pF
C <sub>0_LFXO</sub>	Shunt Capacitance	-	2	pF
R <sub>S_LFXO</sub>	Equivalent series resistance	-	100	kΩ
C <sub>pin</sub>	Input Capacitance on XL1 & XL2 pads	4	-	pF

Table 9: 32.768 kHz Crystal (LFXO)

#### 3.7.2 32.768 kHz clock source comparison

Symbol	Parameter	Min.	Тур.	Max.	Unit
I <sub>LFXO</sub>	Current for 32.768 kHz Crystal Oscillator	-	0.23	-	μA
ILFRC	Current for 32.768 kHz RC Oscillator	-	0.7	1	μA
ILFSYNT	Current for 32.768 kHz Synthesized Oscillator	-	100	-	μA
$f_{\text{TOL_LFXO_BLE}}$	Frequency Tolerance, 32.768 kHz Crystal Oscillator (Bluetooth low energy Stack) <sup>1</sup>	-	-	±500	ppm
$f_{\text{TOL\_LFXO\_ANT}}$	Frequency Tolerance, 32.768 kHz Crystal Oscillator (ANT Stack) <sup>1</sup>	-	-	±50	ppm
f <sub>TOL_LFRC</sub>	Frequency Tolerance, 32.768 kHz RC Oscillator	-	-	±5	%
f <sub>TOL_CAL_LFRC</sub>	Frequency tolerance, 32.768 kHz RC after calibration	-	-	±500	ppm
f <sub>TOL_LFSYNT</sub>	Frequency Tolerance, 32.768 kHz Synthesized Oscillator	-	-	±48	ppm

Table 10 – 32.768 kHz Clock source comparison



# 4 Firmware

Projects for the BMD-341 should utilize the Nordic Semiconductor SDK and the nRF52840 tools for new development. This will allow access to the very latest Bluetooth support from Nordic Semiconductor and provide an ongoing path as new features are released.

## 4.1 Factory image

The BMD-341 module is not loaded with a factory firmware image.

## 4.2 SoftDevices

Nordic Semiconductor protocol stacks for Bluetooth and ANT are known as SoftDevices. SoftDevices are pre-compiled, pre-linked binary files. SoftDevices can be programmed in nRF52 series SoCs and are downloadable from the Nordic Semiconductor website. The BMD-341 with the nRF52840 SoC supports the S140 (Bluetooth low energy Central & Peripheral) and S340 (ANT and Bluetooth low energy) SoftDevices.

#### 4.2.1 S140

The SoftDevice S140 is a feature complete Bluetooth 5 qualified protocol stack for the nRF52840 SoC. It supports up to 20 concurrent links in all roles. It supports Bluetooth 5 features: 2 Mbps, Long Range, Advertising Extensions and channel selection algorithm #2. The number of connections and bandwidth per connection are configurable, offering memory and performance optimization.

It is a complete stack with GAP, GATT, ATT, SM, L2CAP, and Link Layer. Both GATT Server and Client are supported. The broad feature set also includes Privacy 1.2, LE Data Length Extension (DLE), configurable ATT MTU, L2CAP connection-oriented channels and LE Secure Connections.

SoftDevice S140 is available for download here.

#### 4.2.2 S340

SoftDevice S340 is a combined Bluetooth 5 and ANT<sup>™</sup> protocol stack for the nRF52840 SoC, supporting concurrent operation of the two.

It is a Bluetooth 5 qualified protocol stack that offers up to 20 concurrent links in all roles. It supports all Bluetooth 5 features: 2 Mbps, Long Range, Advertising Extensions and channel selection algorithm #2 (CSA #2). The number of connections and bandwidth per connection is configurable, offering memory and performance optimization.

It is a complete Bluetooth LE stack with GAP, GATT, ATT, SM, L2CAP, and Link Layer. Both GATT Server and Client are supported. The broad feature set also includes Privacy 1.2, LE Data Length Extension (DLE), configurable ATT MTU, L2CAP connection-oriented channels and LE Secure Connections.

It supports all ANT features and offers a variety of network topologies, including peer-to-peer, star and tree. Up to 15 individual channels are available, with broadcast, acknowledged, or burst transfer communication.

SoftDevice S340 is available for download here.



#### 4.2.3 IEEE 802.15.4 (Thread and Zigbee)

IEEE 802.15.4 based protocols, such as Thread and Zigbee, on the BMD-341 are not implemented using a SoftDevice. Nordic Semiconductor provides an IEEE 802.15.4 compliant MAC stack which does not require a SoftDevice to be loaded to operate. Nordic Semiconductor also provides pre-compiled Thread and Zigbee stacks. See the Nordic Semiconductor SDK for more information on developing applications that utilize IEEE 802.15.4. Both allow for concurrent operation with Bluetooth low energy SoftDevices.

#### 4.3 Bluetooth address

The BMD-341 modules are preprogrammed from the factory with a unique public Bluetooth address stored in the UICR. The u-blox organizationally unique identifier is 6C:1D:EB. This is combined with the last six characters of the Bluetooth address that are printed on a 2D barcode and in human-readable text on the module label, as described in section 5.3 below.

UICR Register	Address	Description
NRF_UICR + 0x80	0x10001080	Bluetooth_addr [0] (0xCC)
NRF_UICR + 0x81	0x10001081	Bluetooth_addr [1] (0xBB)
NRF_UICR + 0x82	0x10001082	Bluetooth_addr [2] (0xAA)
NRF_UICR + 0x83	0x10001083	Bluetooth_addr [3] (0xEB)
NRF_UICR + 0x84	0x10001084	Bluetooth_addr [4] (0x1D)
NRF_UICR + 0x85	0x10001085	Bluetooth_addr [5] (0x6C)

Table 11: Bluetooth address



# **5** Mechanical specifications

## 5.1 Dimensions

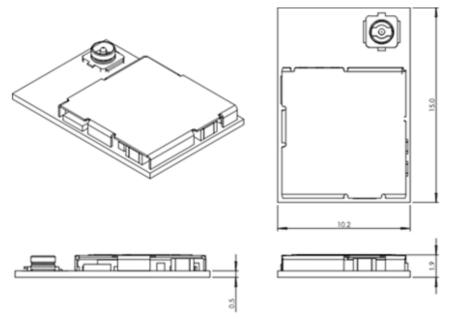
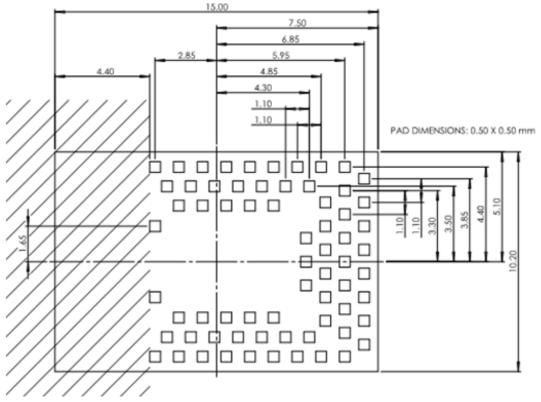


Figure 11: BMD-341 mechanical drawing

## 5.2 Recommended PCB land pads



#### Figure 12: Recommended PCB land pads

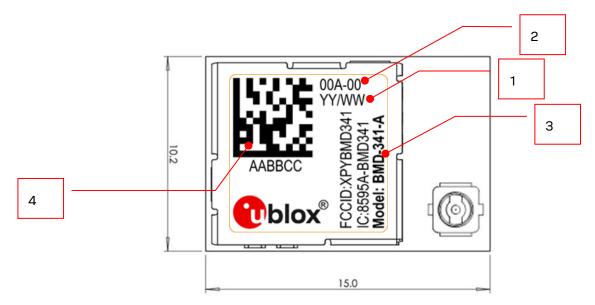
There is no RF Keep-out area for BMD-341.



#### 5.3 Module marking

The labels of the BMD-341 modules include important product information, as described in this section.

Figure 13 illustrates the label of the BMD-341 modules, which includes the u-blox logo, product version, product name, Bluetooth address, and certification numbers.



#### Figure 13: Module marking

Reference	Description
1	Date of unit production (year/week)
2	Product version
3	Product name
4	Data Matrix with unique serial number of 6 alphanumeric symbols, also in human-readable form. The full Bluetooth address consists of the u-blox IEEE OUI (6C:1D:EB) with the six symbols appended: 6C:1D:EB:AA:BB:CC

Table 12: BMD-341 label description



# 6 RF design notes

# 6.1 Recommended RF layout and ground plane

Since the BMD-341 relies on an external antenna, there are no ground plane requirements or keep-out area for the module itself. Refer to the external antenna datasheet for antenna placement and grounding recommendations.

#### 6.2 Mechanical enclosure

For the BMD-341, refer to the external antenna datasheet for placement in or on a mechanical enclosure.

## 6.3 Approved external antennas

#	Mfg.	Part Number	Max Gain	Туре	Size	Approvals
1	Pulse	W1030	2 dBi	1/4 Wave Dipole – Whip	Length: 108.3mm	FCC, ISED, MIC
2	Taoglas	FXP73.07.0100A	2.5 dBi	1/4 Wave Dipole – Flex	7 mm x 47 mm x 0.1 mm	FCC, ISED, MIC
3	Pulse	W1027	3.2 dBi	1/4 Wave Dipole – Whip	Length: 136.8mm	FCC, ISED, MIC
4	Kinsun	6670113050-145	2.0 dBi	1/4 Wave Dipole – PCB	12 mm x 65 mm x 0.46 mm	FCC, ISED, MIC

The antennas listed below were tested for use with the BMD-341.

Table 13: BMD-341 Approved external antennas



# 7 BMD-341 evaluation development kit

u-blox has developed full featured evaluation boards that provide a complete I/O pin out to headers, on-board programming and debugging, 32.768 kHz crystal, power and virtual COM port over USB, BMD-341 USB connector, 64 Mb quad SPI Flash, four user LEDs, and four user buttons. The evaluation boards also provide the option to be powered from a CR2032 coin cell battery or a LiPo battery through a JST-PH connecter and have current sense resistors and headers to allow for convenient current measurements. Arduino Mega style headers are provided for easy prototyping of additional functions. The evaluation boards also support programming off-board BMD-3xx series modules.



Figure 14: BMD-341 evaluation board



# 8 Qualification and approvals

# 8.1 United States (FCC):

The BMD-341 module has received Federal Communications Commission (FCC) CFR47 Telecommunications, Part 15 Subpart C "Intentional Radiators" modular approval in accordance with Parts 15.212 and 15.247. The modular approval allows the end user to integrate the module into a finished product without obtaining subsequent and separate FCC approvals for intentional radiation, provided no changes or modifications are made to the module circuitry. Changes or modifications could void the user's authority to operate the equipment. The end user must comply with all of the instructions provided by the Grantee, which indicate installation and/or operating conditions necessary for compliance.

The finished product is required to comply with all applicable FCC equipment authorizations regulations, requirements and equipment functions not associated with the transmitter module portion. For example, compliance must be demonstrated to regulations for other transmitter components within the host product; to requirements for unintentional radiators (Part 15 Subpart B "Unintentional Radiators"), such as digital devices, computer peripherals, radio receivers, etc.; and to additional authorization requirements for the non-transmitter functions on the transmitter module (that is, Verification, or Declaration of Conformity) (for example, transmitter modules may also contain digital logic functions) as appropriate.

- Modification to this product will void the users' authority to operate this equipment.
- The OEM is still responsible for verifying end product compliance with FCC Part 15, subpart B limits for unintentional radiators through an accredited test facility.

KDB 996369 D03 sections 2.4 (limited module procedures) and 2.5 (trace antenna designs) are not applicable to the BMD-341.

#### 8.1.1 Labeling and user information requirements

#### The BMD-341 is assigned the FCC ID number: XPYBMD341

If the FCC ID is not visible when the module is installed inside another device, then the outside of the finished product into which the module is installed must also display a label referring to the enclosed module. This exterior label can use the following or similar wording:

#### Contains FCC ID: XPYBMD341

In addition to marking the product with the appropriate FCC ID, the end product shall bear the following statement in a conspicuous location on the device (FCC Rules, Title 47, Subchapter A, Part 15, Subpart B, Chapter §15.19):

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

#### 8.1.2 RF exposure

All transmitters regulated by FCC must comply with RF exposure requirements. KDB 447498 General RF Exposure Guidance provides guidance in determining whether proposed or existing transmitting facilities, operations or devices comply with limits for human exposure to Radio Frequency (RF) fields adopted by the Federal Communications Commission (FCC).

This module is approved for installation into mobile and/or portable host platforms and must not be co-located or operating in conjunction with any other antenna or transmitter except in accordance



with FCC multi-transmitter guidelines. End users must be provided with transmitter operating conditions for satisfying RF Exposure compliance.

# 8.2 Canada (ISED)

The BMD-341 module is certified for use in Canada under Innovation, Science and Economic Development Canada (ISED) Radio Standards Specification (RSS) RSS-247 Issue 2 and RSSGen.

#### 8.2.1 Labeling and user information requirements

#### The BMD-341 is assigned the IC ID number: 8595A-BMD341

Labeling Requirements for the Host Device (from Section 3.2.1, RSS-Gen, Issue 3, December 2010): The host device shall be properly labeled to identify the module within the host device. The Industry Canada certification label of a module shall be clearly visible at all times when installed in the host device, otherwise the host device must be labeled to display the Industry Canada certification number of the module, preceded by the words "Contains transmitter module", or the word "Contains", or similar wording expressing the same meaning, as follows:

Contains transmitter module IC: 8595A-BMD341

User Manual Notice for License-Exempt Radio Apparatus (from Section 7.1.3 RSS-Gen, Issue 3, December 2010): User manuals for license-exempt radio apparatus shall contain the following or equivalent notice in a conspicuous location in the user manual or alternatively on the device or both:

This device complies with Industry Canada license exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes: (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Transmitter Antenna (from Section 7.1.2 RSS-Gen, Issue 3, December 2010): User manuals for transmitters shall display the following notice in a conspicuous location:

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication.

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante.

#### 8.2.2 RF exposure

All transmitters regulated by ISED must comply with RF exposure requirements listed in RSS-102 -Radio Frequency (RF) Exposure Compliance of Radiocommunication Apparatus (All Frequency Bands). This module is approved for installation into mobile host platforms and must not be colocated or operating in conjunction with any other antenna or transmitter except in accordance with Industry Canada's multi-transmitter guidelines. A minimum 20 cm separation distance between any



nearby person and the transmitter or antenna shall be maintained. End users must be provided with transmitter operating conditions for satisfying RF Exposure compliance.

# 8.3 Europe (CE-RED)

The BMD-341 is a Radio Equipment Directive assessed radio module that is CE complaint and have been manufactured and tested with the intention of being integrated into a final product.

The BMD-341 has been tested to current Radio Equipment Directives

#### EU - Radio Equipment Directive 2014/53/EU

- ETSI EN 300 328 V 2.1.1
- ETSI EN 301 489-1 V2.1.1
- ETSI EN 301 489-17 V3.1.1

The Radio Equipment Directive – Compliance Association (RED-CA) provides guidance on modular devices at the RED-CA website: http://www.redca.eu/Pages/Documents%201.htm.

#### 8.3.1 Labeling and user information requirements

The label on the final products which contain a u-blox module must follow CE marking requirements. The "R&TTE Compliance Association Technical Guidance Note 01" provides guidance on final product CE marking.

## 8.4 Australia / New Zealand (RCM)

The BMD-341 has been tested to comply with the AS/NZS 4268:2017, Radio equipment and systems – Short range devices – Limits and methods of measurement. The report may be obtained from your local FAE., and may be used as evidence in obtaining permission to use the Regulatory Compliance Mark (RCM).

Information on registration as a Responsible Party, license and labeling requirements may be found at the following websites:

Australia: http://www.acma.gov.au/theACMA/radiocommunications-short-range-devices-standard-2004

#### New Zealand: http://www.rsm.govt.nz/compliance

Only Australian-based and New Zealand-based companies who are registered may be granted permission to use the RCM. An Australian-based or New Zealand-based agent or importer may also register as a Responsible Party to use the RCM on behalf of a company not in Australia or New Zealand.

## 8.5 Bluetooth qualification

- The Bluetooth SIG maintains the Bluetooth Specification, and ensures that products are properly tested and comply with the Bluetooth license agreements. Companies that list products with the Bluetooth SIG are required to be members of the SIG and submit the listed fees. Refer to this link for details: https://www.bluetooth.com/develop-with-bluetooth/qualification-listing
- The BMD-341 Bluetooth low energy module based on the Nordic Semiconductor nRF52840 is listed as a "Tested Component", with Qualified Design IDs (QDID) 95452. This allows an end-product based on a BMD-341 module to inherit the component listings without the need to run through all of the tests again. The end-product will often inherit several QDIDs, and are identified on a "Declaration of Compliance". Refer to the BMD-3xx System Integration Manual for details on creating an end product declaration.
- The BMD-341 primarily utilizes the S140 SoftDevice.



# 9 Environmental

## 9.1 RoHS

The BMD-341 module is in compliance with Directive 2011/65/EU, 2015/863/EU of the European Parliament and the Council on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

# 9.2 REACH

BMD-341 modules do not contain the 201 SVHC (Substance of Very High Concern), as defined by Directive EC/1907/2006 Article according to REACH Annex XVII.

# 9.3 California proposition 65 (P65)

This product can expose you to Nickel (metallic), which is known to the State of California to cause cancer. For more information go to www.P65Warnings.ca.gov. Warnings are not required where the listed chemical is inaccessible to the average user of the end product.



# **10 Product handling**

# 10.1 Packaging

# 10.2 Reel packaging

Modules are packaged on 330 mm reels loaded with 1000 modules. Each reel is placed in an antistatic bag with a desiccant pack and humidity card and placed in a 340x350x65 mm box. An antistatic warning and reel label are adhered to the outside of the bag.

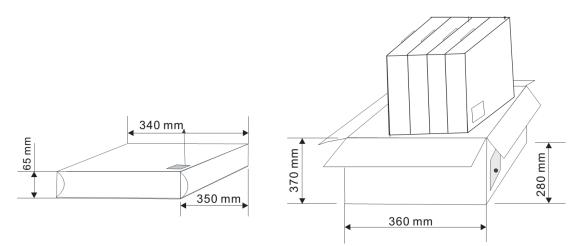
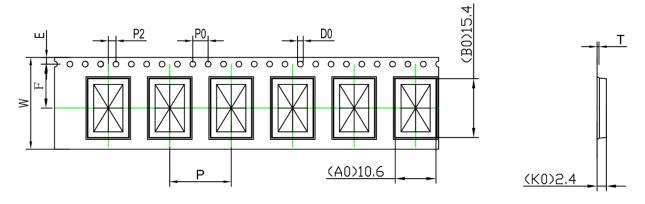


Figure 15 – Reel cartons

## 10.3 Carrier tape dimensions



ITEM	W	A	Bo	K₀	K1	Р	F	E	$\mathbf{D}_{o}$	$\mathbf{D}_{1}$	$P_{\circ}$	Pa	Т
DIM	24.0 <sup>+0.30</sup>	10.60 <sup>±0.10</sup>	15.4 <sup>+0.10</sup> -0.10	2.40 <sup>+0.10</sup> -0.10	10.00	16.0	11.5	1.75 <sup>+0.10</sup> -0.10	1.50 <sup>+0.10</sup> -0.00	0.00 <sup>+0.10</sup> -0.00		12.00	
ALTERNATE													

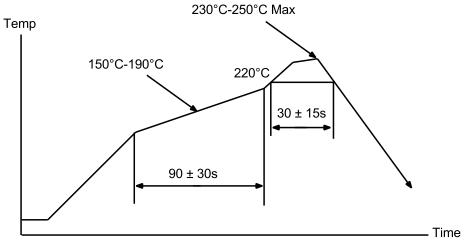
Figure 16 – Carrier tape dimensions

## 10.4 Moisture sensitivity level

The BMD-341 is rated for MSL 3, 168-hour floor life after opening.



# 10.6 Reflow soldering



#### Figure 17: Reflow Profile for lead free solder



# 11 Labeling and ordering information

## 11.1 Batch Label

Figure 18 shows an example of the layout and contents of the batch label. The label is affixed to reels, sealed bags, and individual packing cartons (inner cartons).



Figure 18: Batch label example

# 11.2 Multipack label

Figure 19 shows an example of the layout and contents of the multipack label. The label is affixed to shipping parcels (outer cartons).



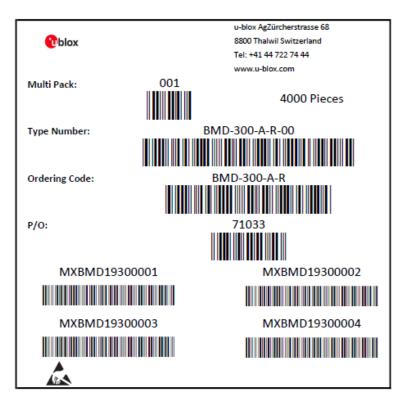


Figure 19: Multipack label example

# 11.3 Ordering information

Ordering Code	Product
BMD-341-A-R	BMD-341 module, Rev A, nRF52840-QIAA, Tape & Reel, 1000 piece multiples
BMD-341-EVAL	BMD-341-A Evaluation Kit w/ SEGGER J-Link-OB debug probe

Table 14: Product ordering codes



# 12 Support and other high-risk use warning

This product is neither designed nor intended for use in a life support device or system, nor for use in other fault-intolerant, hazardous or other environments requiring fail-safe performance, such as any application in which the failure or malfunction of the product could lead directly or indirectly to death, bodily injury, or physical or property damage (collectively, "high-risk environments").

u-blox expressly disclaims any express or implied warranty of fitness for use in high-risk environments.

The customer using this product in a high-risk environment agrees to indemnify and defend u-blox from and against any claims and damages arising out of such use.



# **Related documents**

- [1] u-blox Package Information Guide, Doc. No. UBX-14001652
- [2] Nordic Semiconductor, nRF52840 Product Specification
- [3] Nordic Semiconductor, nRF5 Software Development Kit

# **Revision history**

Revision	Date	Name	Comments
0.5	16-Apr-2019		Preliminary release for engineering samples.
1.0	01-Jul-2019		Updated Nordic Semiconductor links Updated HV power output specifications Updated RC Oscillator specifications Updated images throughout
R03	27-Sep-2019		Document converted from Rigado to u-blox style data sheet.

For regular updates to u-blox documentation and to receive product change notifications, register on our homepage (www.u-blox.com).



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